	nnel Enhand	ement Mode	MOSFET-	-				
Voltage	50 V	Current	360 mA		OT-563	Unit : inch(mm ବ୍ୟୁକ୍ର		
Features					0.052(1.3			
• RDS(ON) , \	/GS@10V, ID@	500mA<1.45Ω			0.059(1.70) 0.059(1.50) 0.035(0.90) 0.035(0.90)			
• RDS(ON) , \	/GS@4.5V, ID@	200mA<1.95Ω						
<ul> <li>RDS(ON) , VGS@2.5V, ID@100mA&lt;4.0Ω</li> </ul>					_	0.002(0.07)		
<ul> <li>RDS(ON) , VGS@1.8V, ID@10mA&lt;6.0Ω</li> </ul>								
Advanced Trench Process Technology					0.067(1.7			
<ul> <li>ESD Protect</li> </ul>	ted 2KV HBM							
• Specially Designed for Relay driver, Speed line drive, etc.								
<ul> <li>Lead free in compliance with EU RoHS 2.0</li> </ul>								
<ul> <li>Green molding compound as per IEC 61249 standard</li> </ul>					0.012(0.30) 0.004(0.10)	_		
Mechanica	al Data				D1 6	G2 S2 5 4		
• Case : SOT-	-563 Package							
• Terminals : Solderable per MIL-STD-750, Method 2026					│ │ <del>│ ↓</del> └┶─┤ं <u></u> ₽┘ ╈ │ │ <b>ቚ</b> ┌──┤────────────────────────────			
Approx. Weight : 0.0026 grams								
Marking : X38					1	2 3		

# Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAM	SYMBOL	LIMIT	UNITS	
Drain-Source Voltage	V <sub>DS</sub>	50	V	
Gate-Source Voltage	V <sub>GS</sub>	<u>+</u> 20	V	
Continuous Drain Current	ID	360	mA	
Pulsed Drain Current	I <sub>DM</sub>	1200	mA	
	T <sub>A</sub> =25°C		300	mW
Power Dissipation	Derate above 25°C	PD	2.4	mW/ºC
Operating Junction and Storag	e Temperature Range	TJ,TSTG	-55~150	٥C
Typical Thermal Resistance - Junction to Ambient <sup>(Note 3)</sup>	R <sub>0JA</sub>	417	°C/W	



#### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

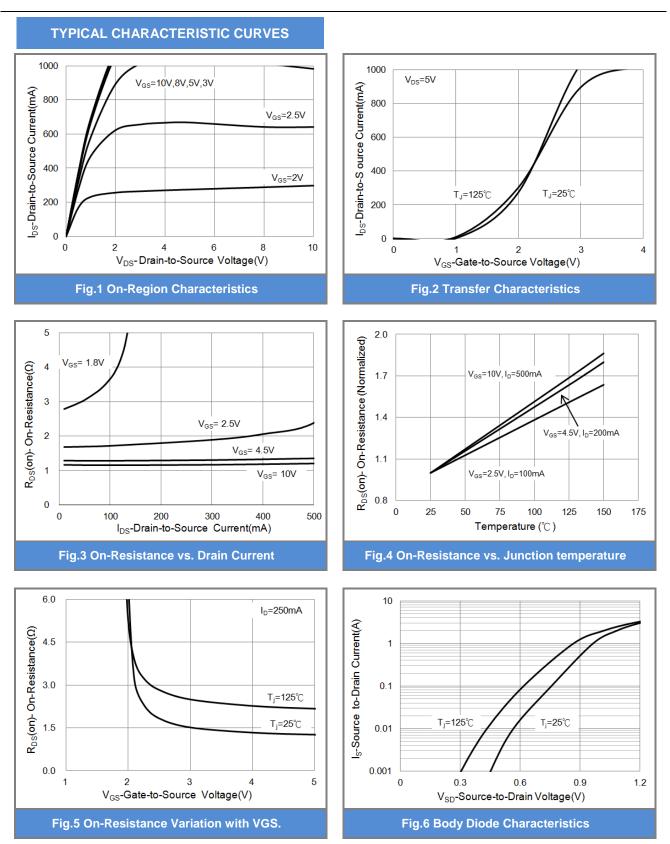
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	50	-	-	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.5	0.86	1.0	V	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V,I <sub>D</sub> =500mA	-	1.2	1.45	- Ω	
		V <sub>GS</sub> =4.5V,I <sub>D</sub> =200mA	-	1.3	1.95		
		V <sub>GS</sub> =2.5V,I <sub>D</sub> =100mA	-	1.7	4.0		
		$V_{GS}$ =1.8V,I <sub>D</sub> =10mA	-	4.0	6.0		
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V	-	-	1	uA	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = <u>+</u> 20V,V <sub>DS</sub> =0V	-	-	<u>+</u> 10	uA	
Dynamic <sup>(Note 4)</sup>							
Total Gate Charge	Qg		-	0.95	-	nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =25V, I <sub>D</sub> =500mA, V <sub>GS</sub> =4.5V	-	0.34	-		
Gate-Drain Charge	Q <sub>gd</sub>	VGS=4.5V	-	0.32	-		
Input Capacitance	Ciss		-	36	-	pF	
Output Capacitance	Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	11	-		
Reverse Transfer Capacitance	Crss		-	6.6	-		
Turn-On Delay Time	td <sub>(on)</sub>		-	2.3	-		
Turn-On Rise Time	tr	V <sub>DD</sub> =25V, I <sub>D</sub> =500mA, V <sub>GS</sub> =10V,	-	20	-	ns	
Turn-Off Delay Time	td <sub>(off)</sub>	$V_{GS} = 10V$ , R <sub>G</sub> =6 $\Omega^{(Note 1,2)}$	-	7	-		
Turn-Off Fall Time	tf	KG=012(1000 1)=)	-	20	-		
Drain-Source Diode			_	_	_	_	
Maximum Continuous Drain-Source Diode Forward Current	ls		-	-	500	mA	
Diode Forward Voltage	V <sub>SD</sub>	Is=500mA, V <sub>GS</sub> =0V	-	0.9	1.5	V	

NOTES :

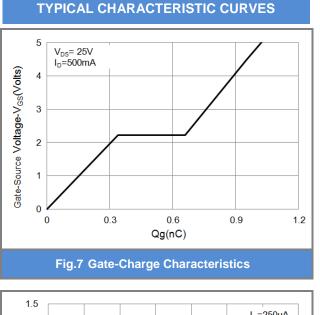
1. Pulse width

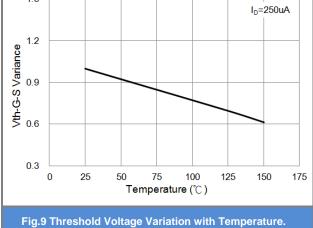
- 2. Essentially independent of operating temperature typical characteristics.
- 3. R<sub>®JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. mounted on a 1 inch square pad of copper
- 4. Guaranteed by design, not subject to production testing.

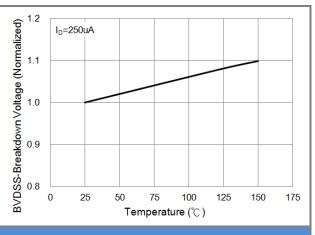




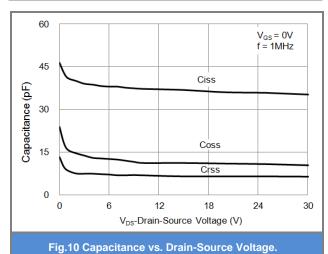










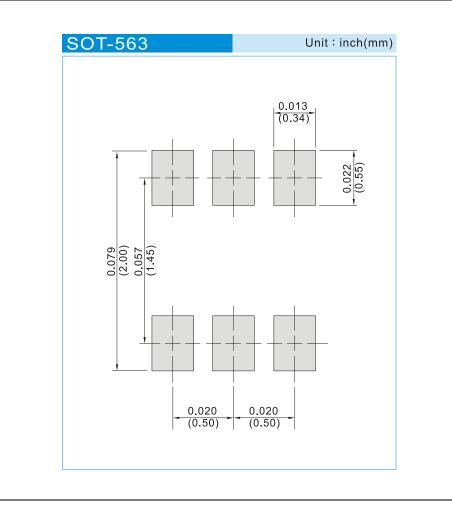




#### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking
PJX8838	SOT-563	4K pcs / 7" reel	X38
PJX8838	SOT-563	10K pcs / 13" reel	X38

#### **Mounting Pad Layout**





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